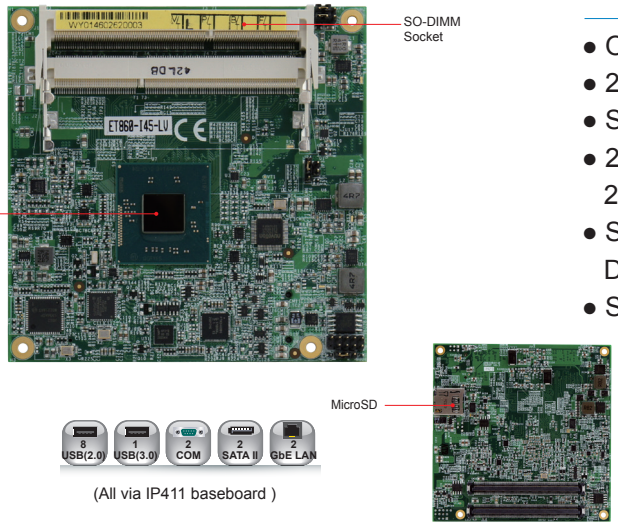
ET860

Intel® Atom™ E3845/E3827 SoC COM Express Compact Module (Type 6)

Wide Temperature



(All via IP411 baseboard)

Features

- Onboard Intel® Atom™ E3845/E3827 SoC
- 2x DDR3L SO-DIMM, Max. 8GB
- Single Gigabit LAN via baseboard (IP411)
- 2x SATA II, 1x USB 3.0, 8x USB 2.0, 2x COM via baseboard (IP411)
- Supports 2x independent displays, DisplayPort/CRT/LVDS via baseboard (IP411)
- Supports HD audio via baseboard (IP411)

System

CPU type	Intel® Atom™ E3845/E3827 SoC on board
System Memory	2x DDR3L@1.35V SO-DIMM, Max. 8GB (Non-ECC)
System Chipset	Integrated in Intel® Atom™ SoC
BIOS	AMI BIOS
Watchdog Timer	256 levels
SSD	N/A
H/W Monitor	Yes
Expansion Slot	1x PCI-E(x1) on baseboard (IP411)

Graphics

VGA Controller	Intel® Atom™ E3845/E3827 SoC integrated graphics supports CRT, DisplayPort & LVDS
VGA Memory	Shared memory
Display Interface	24-bit single channel LVDS on baseboard (IP411)

LAN

Controller	1x Intel® I210IT Gigabit LAN
Connector	1x RJ45 on baseboard (IP411)

Multi I/O

I/O Chipset	Nuvoton NCT5523D on board (supports Tx/Rx only) functions on baseboard (IP411) include: 1x LPT, 2x SATA II, 2x RS232 (full function)
USB	1x USB 3.0 ports via baseboard (IP411) 8x USB 2.0 ports via baseboard (supports 6x USB 2.0 only on IP411)
Audio	Intel® Atom™ E3845/E3827 SoC built-in audio w/ Realtek ALC662 codec on baseboard (IP411)
Others	MicroSD slot onboard@ rear side Digital I/O (4 in / 4 out) on baseboard (IP411)

Mechanical and Environmental

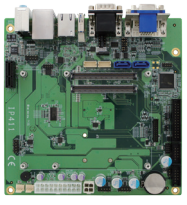
Dimensions	95mm x 95mm (3.74" x 3.74")
Max. Power Requirement	Intel® Atom™ E3845 1.91GHz w/ 2x 2GB DDR3L-1600 +12V : 0.91A ; +5V : 0.13A +3.3V : 0.24A ; +5VSB : 0.05A
Operating Temperature	-40°C~85°C (-40°F~185°F)
Storage Temperature	-40°C~90°C (-40°F~194°F)
Relative Humidity	90% (non-condensing @60°C)

Ordering Information

ET860-i45-LV	COM Express (Type 6) module with Intel® Atom™ E3845 (1.91GHz) SoC, DDR3L dual channel memory, LVDS
ET860-i27-LV	COM Express (Type 6) module with Intel® Atom™ E3827 (1.75GHz) SoC, DDR3L dual channel memory, LVDS
IP411	Mini-iTX COM Express (Type 6) baseboard
HSET860-BGA-1	Heatsink for ET860
HSET860-BGA-2	Heat spreader for ET860

IP411

Mini-ITX COM Express (Type 6) Baseboard



Features

- Mini-ITX Express Baseboard for Compact Size COMe module
- Supports DVI-D, VGA 24-bit dual channel LVDS
- Onboard dual PCI-E Gigabit LAN
- 4x COM, 1x printer port, 1x USB3.0, 6x USB2.0, 2x SATAII
- 1x PCI-E(1x), 1x Mini-PCI-E (Full Size)
- ATX power connector
- 170mm x 170mm

Remarks: 1. Specifications are subject to change without prior notice. 2. ODM/OEM is available. 3. For user's manual & datasheet download, visit www.ibase.com.tw.